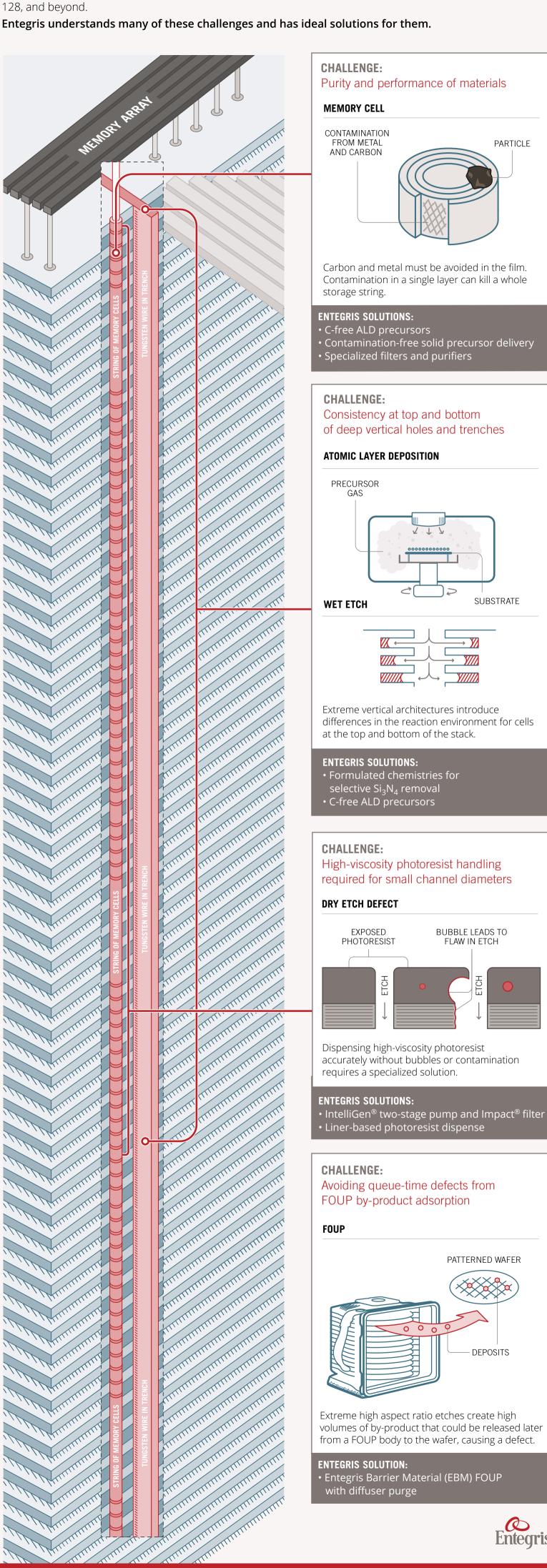
Entegris Solutions for the Unique Challenges of 3D NAND Design and Manufacturing

Three-dimensional vertically-stacked memory architectures offer exponential gains in flash memory storage, but they also introduce fundamental new challenges at the device fabrication and integration level. These challenges affect all aspects of the flash memory product chain, from design to supply to material handling, manufacturing, and delivery. These challenges become more acute as architectures are pushed from 64 vertical layers to 96,





• Entegris Barrier Material (EBM) FOUP

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